

4

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RELEASED FOR PUBLICATION

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LOC

DIST

REVISIONS

P

LTR

DESCRIPTION

DATE

DWN

APVD

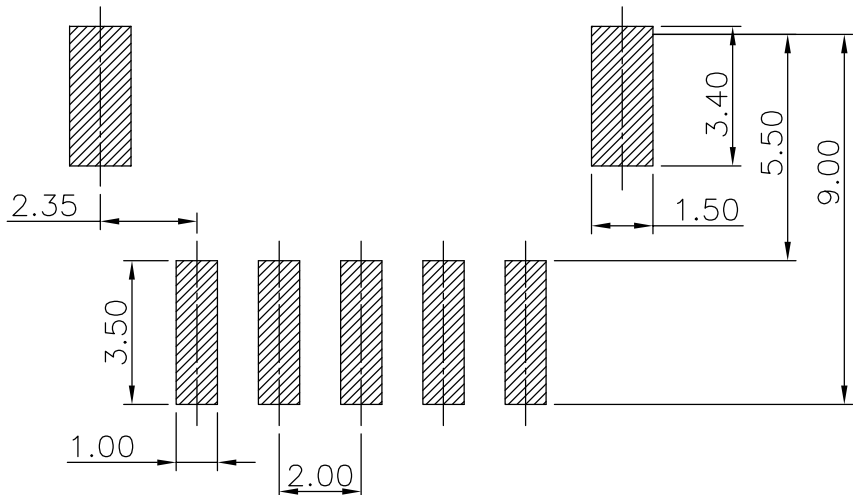
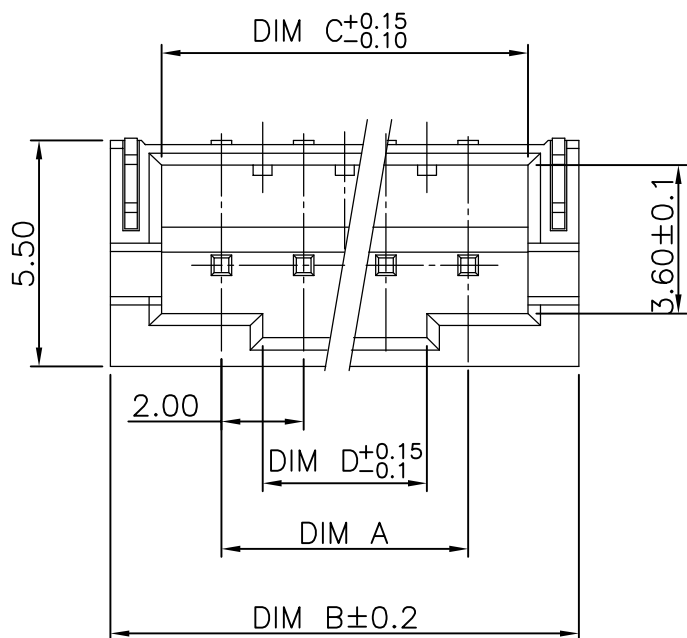
A4

RELEASED (ECR-15-015517)

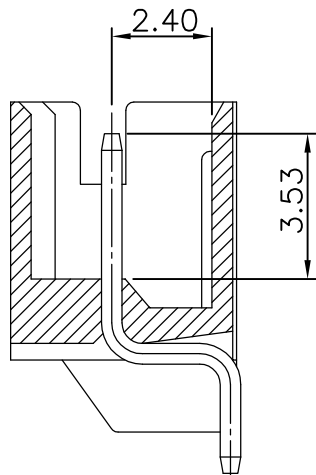
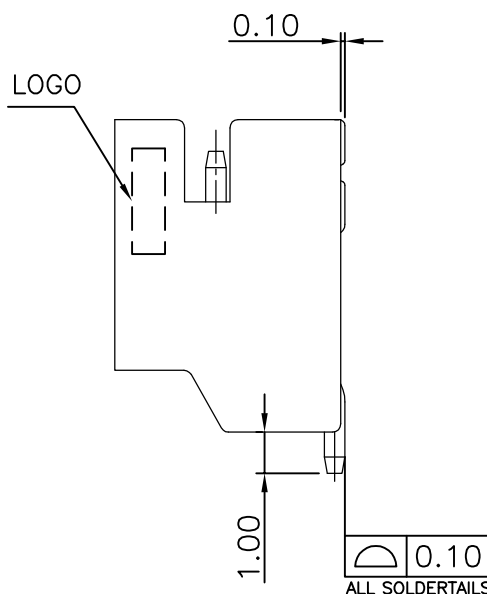
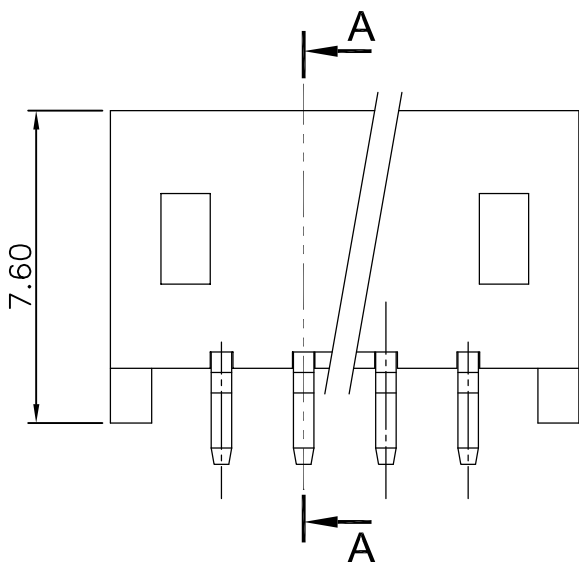
22OCT15

A.Z

WK



RECOMMENDED PCB LAYOUT



SECTION A-A

NOTE:

1. MATERIAL :

HOUSING : PA9T, UL 94V-0, COLOR: NATURAL.

CONTACT : BRASS, THICKNESS=0.50mm.

2. FINISH:

CONTACT : Δ 2 μ m [80u"] MIN. MATTE TIN PLATED OVER

1.27 μ m [50u"] MIN. NICKEL UNDERPLATED ALL OVER.

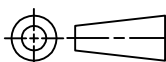
Δ GOLD FLASH OVER 1.27 μ m [50u"] MIN. NICKEL UNDERPLATED ALL OVER.

3. REFLOW SOLDER CAPABLE TO 260°C PER TE CONNECTIVITY SPEC 109-201, CONDITION B.

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:

MM



MATERIAL

SEE NOTE

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC $\pm$ —
1 PLC $\pm$ 0.25
2 PLC $\pm$ 0.15
3 PLC $\pm$ 0.05
4 PLC $\pm$ —
ANGLES $\pm$ 3°

FINISH

SEE NOTE

DWN O. HU 01NOV2006

CHK S. HOU 01NOV2006

APVD W.J. KE 01NOV2006

PRODUCT SPEC

108-57100

QUALIFICATION TEST REPORT

501-57058

WEIGHT

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CUSTOMER DRAWING



TE Connectivity

NAME

HPI CONN., 2.0MM PITCH,
R/A, SMT TYPE

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

C=1775469

—

SCALE

—

SHEET

1 OF 2

REV

A4

